

DOT MATRIX DISPLAY

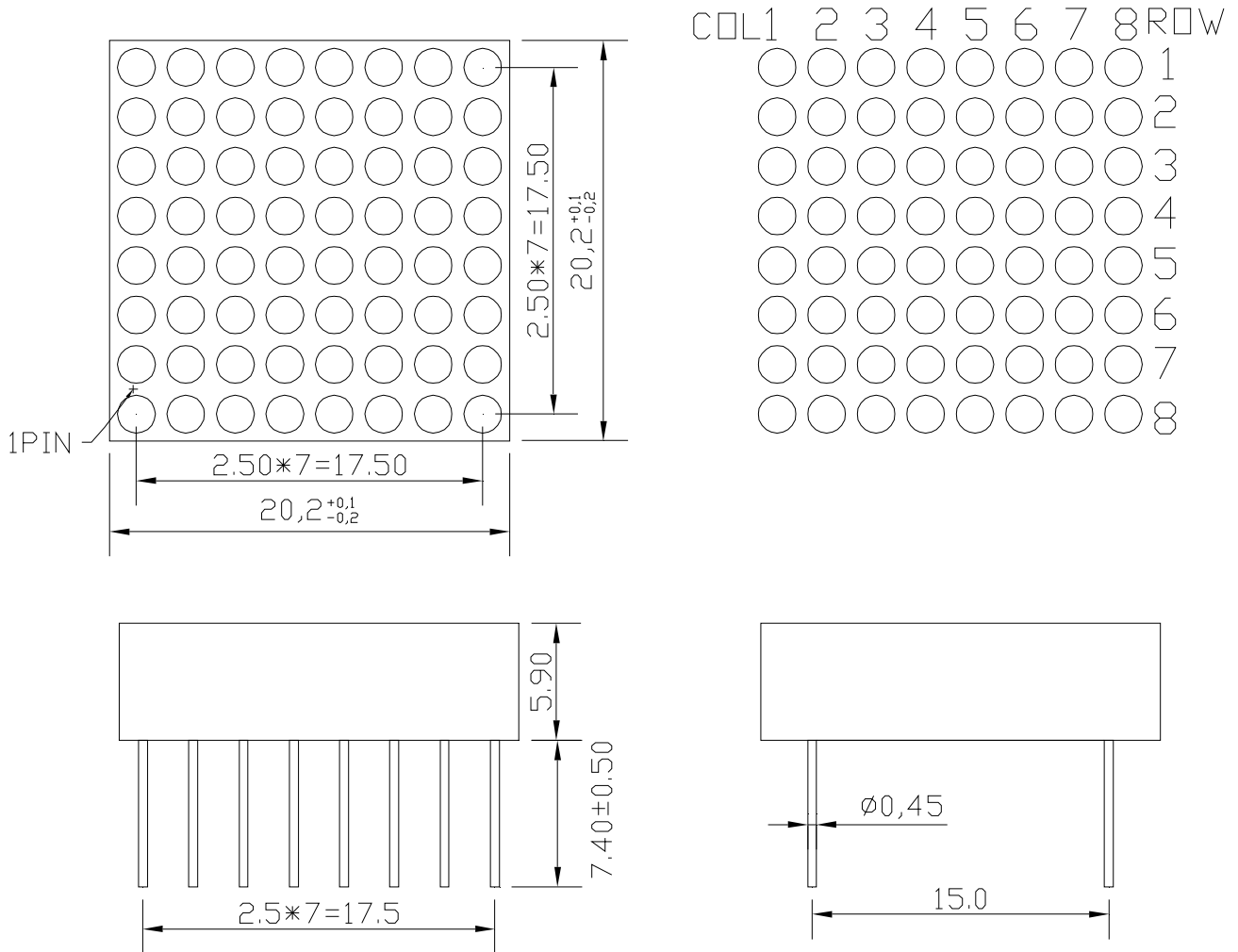
JZM07880AO-BW

DATA SHEET

DOCUMENT NO.: WI-RD-LDS-07880AO-BW**RELEASE DATE: 2007-9-21****VERSION: A/0****RD No.: JZD20070921004**

PART NO.: JZM07880AO-BW

Package Dimensions



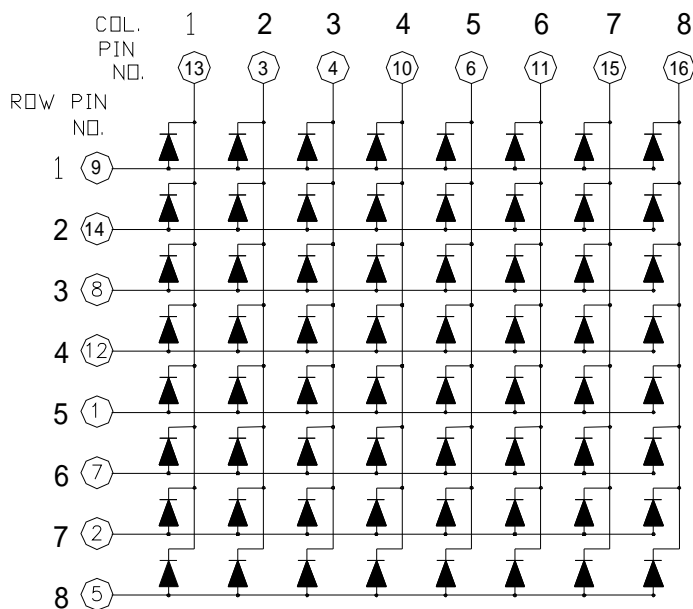
Notes:

1. All dimension are in millimeters and(Inch)tolerance is ± 0.25 mm unless otherwise noted.
2. Specifications are subject to change without notice.

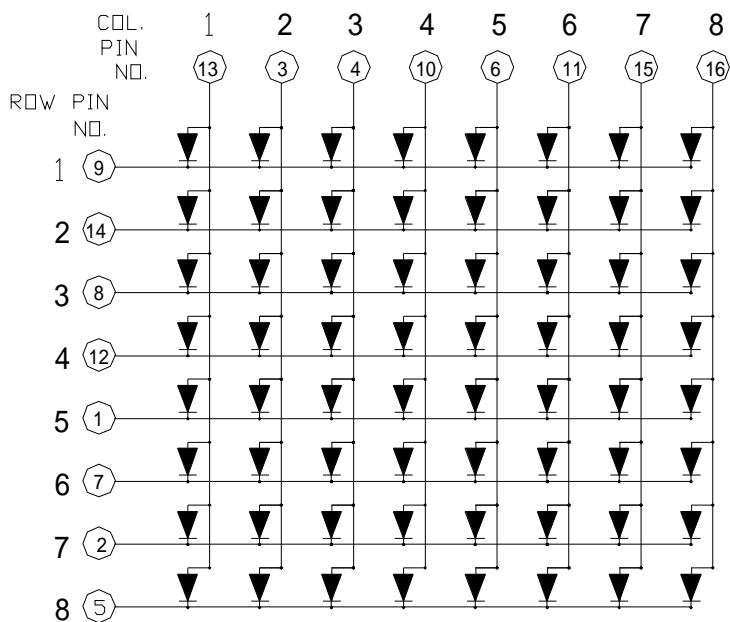
PART NO.: JZM07880AO-BW

Internal Circuit Diagram

JZM07880AO-BW



JZM07880BO-BW



PART NO.: JZM07880AO-BW

Electrical Connection

| PIN NO. | JZM07880AO-BW | PIN NO. | JZM07880BO-BW |
|---------|------------------|---------|----------------|
| 1 | Anode Row 5 | 1 | Cathode Row 5 |
| 2 | Anode Row 7 | 2 | Cathode Row 7 |
| 3 | Cathode Column 2 | 3 | Anode Column 2 |
| 4 | Cathode Column 3 | 4 | Anode Column 3 |
| 5 | Anode Row 8 | 5 | Cathode Row 8 |
| 6 | Cathode Column 5 | 6 | Anode Column 5 |
| 7 | Anode Row 6 | 7 | Cathode Row 6 |
| 8 | Anode Row 3 | 8 | Cathode Row 3 |
| 9 | Anode Row 1 | 9 | Cathode Row 1 |
| 10 | Cathode Column 4 | 10 | Anode Column 4 |
| 11 | Cathode Column 6 | 11 | Anode Column 6 |
| 12 | Anode Row 4 | 12 | Cathode Row 4 |
| 13 | Cathode Column 1 | 13 | Anode Column 1 |
| 14 | Anode Row 2 | 14 | Cathode Row 2 |
| 15 | Cathode Column 7 | 15 | Anode Column 7 |
| 16 | Cathode Column 8 | 16 | Anode Column 8 |

Absolute Maximum Rating at=Ta=25°C

| Parameter | Symbol | Ratings | UNIT |
|---------------------------------|--------|---------|------|
| | | SGM | |
| Forward Current Per Chip | IF | 30 | mA |
| Peak Forward Current Per Chip*1 | IFP | 100 | mA |
| Power Dissipation Per Chip | PD | 100 | mW |
| Reverse Current Per Any Chip | Ir | 50 | uA |
| Electrostatic Discharge*2 | ESD | 1000 | V |
| Operating Temperature | Topr | -25~+85 | °C |
| Storage Temperature | Tstg | -25~+85 | °C |

Solder Temperature 1/16 Inch Below Seating Plane For 3 Seconds At 260°C

*1:Duty 1/10,0.1ms Pulse With

*2:Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing these LED. All devices, equipment and machinery must be properly grounded.

PART NO.: JZM07880AO-BW

Part selection And Application Information(Ratings at 25°C)

| PART NO. | COLOR (EPOX Y/SURF ACE) | CHIP | | Common cathode or anode | WD (nm) | Electrical | | | | IV- M |
|---------------|------------------------------------|----------|---------|-------------------------------|----------------|------------|------|---------|------|-----------|
| | | Material | Emitted | | | Vf(v) | | Iv(mcd) | | |
| | | | | | | Typ. | Max. | Min. | Typ. | |
| JZM07880AO-BW | WHITE DIFFUS E/BLAC K | AlGaInP | orange | Common anode | 603 | 1.9 | 2.4 | 50 | 55 | 1: 1.1 |

Note:1.The forward voltage data did not including \pm .01V testing tolerance.

2.The luminous intensity data did not including \pm 15% testing tolerance.

Test Condition For Each Parameter

| Parameter | Symbol | Unit | Test Condition |
|-----------------------------------|--------|---------|----------------|
| Forward Voltage Per Chip | Vf | volt | If=20mA |
| Luminous Intensity Per Chip | Iv | mcd | If=20mA |
| Peak Wavelength | WP | nm | If=20mA |
| Dominant Wavelength | WD | nm | If=20mA |
| Spectral Line Half-Width | ▲W | nm | If=20mA |
| Reverse Current Any Chip | Ir | μ A | If=20mA |
| Luminous Intensity Matching Ratio | IV-M | | |

Typical Optical-Electronic Characteristic Curves

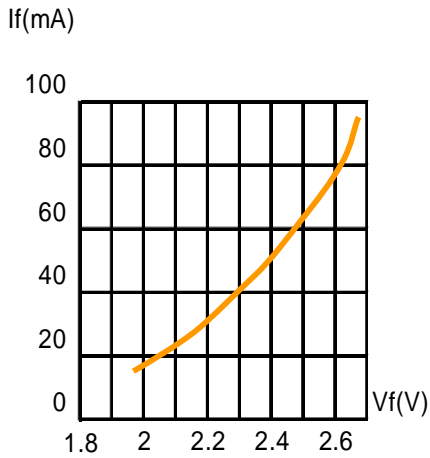


Fig.1 FORWARD CURRENT VS. FORWARD

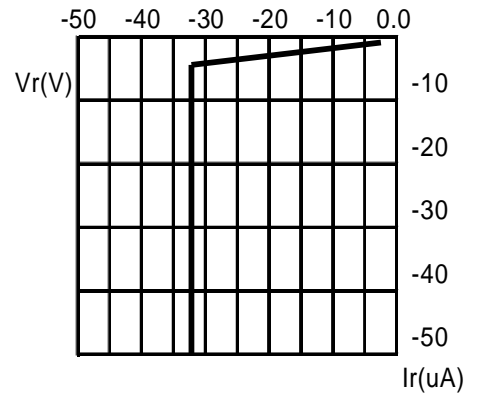
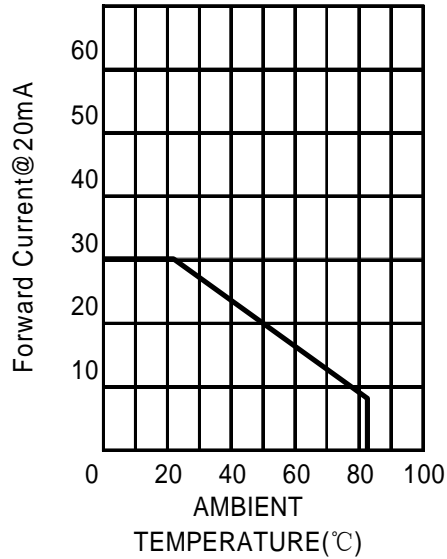


Fig.2 REVERSE CURRENT VS. REVERSE VOLTAGE.

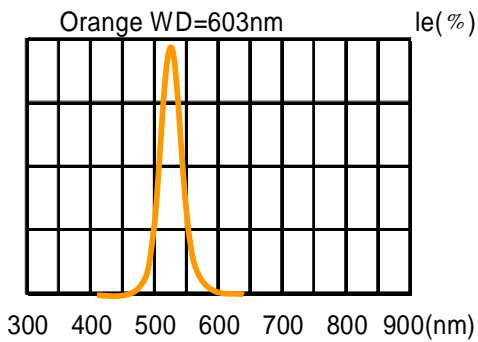
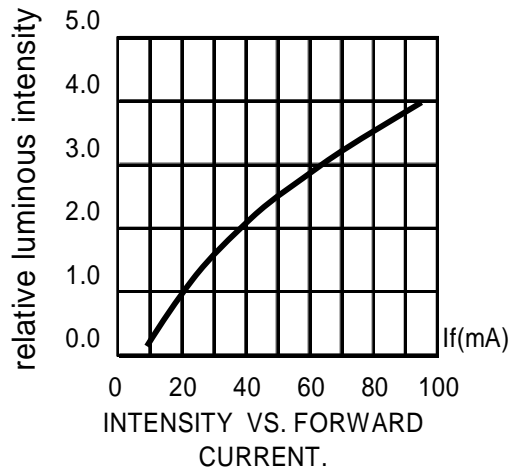


Fig.4 RELATIVE LUMINOUS INTENSITY VS. WAVELENGTH.



Soldering Condition (Pb-Free)

1. Iron:

Soldering Iron: 30W Max

Temperature 350°C Max

Soldering Time: 3 Seconds Max (One time only)

Distance: Solder Temperature 1/16Inch Below Seating Plane

For 3 Seconds At 260°C

2. Wave Soldering Profile

Dip Soldering

Preheat: 120°C Max

Preheat time: 60 seconds Max

Ramp-up

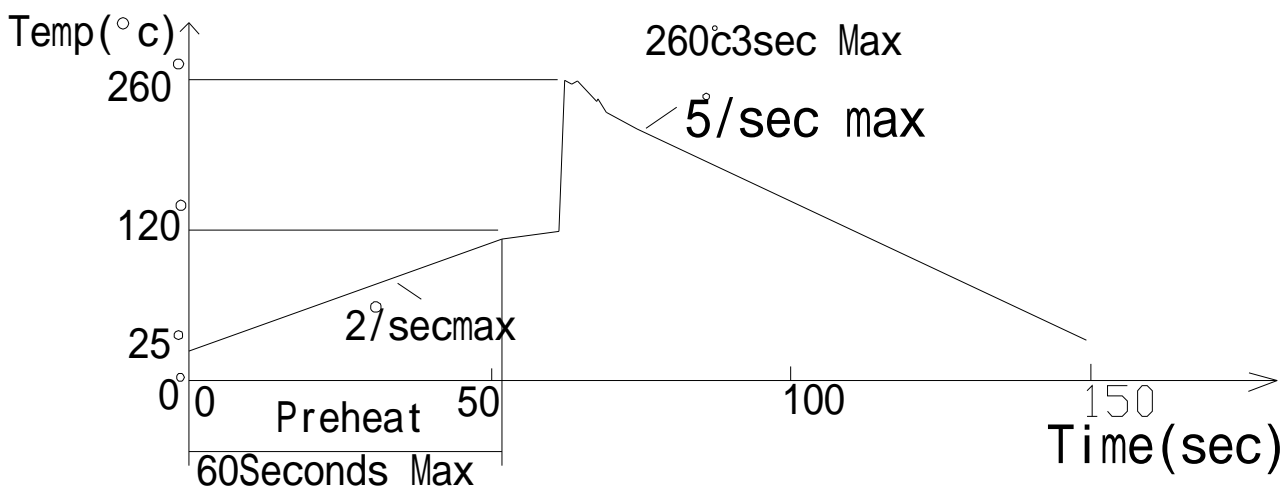
2°C/sec(max)

Ramp-Down: -5°C/sec(max)

Solder Bath: 260°C Max

Dipping Time: 3 seconds Max

Distance: Solder Temperature 1/16Inch Below Seating Plane for 3 Seconds At 260°C



Note: 1. Wave solder should not be made more than one time.

2. You can just only select one of the soldering conditions as above.

Reliability Test:

| Test Item | Standard Test Method | Test Condition | Description |
|-------------------------------------|--|---|--|
| Operating Life Test | JIS C7021:B-1 MIL-STD-750:1026 MIL-STD-883:1005 | 1. Under Room Temperature 2. If=10 mA 3. t=1000hrs(-24hrs,+72hrs) | This test is conducted for the purpose of deteming the resistance of a part in electrical and themal stressed. |
| High Temperature Storage Test | JIS C 7021:B-10 MIL-STD-883:1008 | 1. Ta=105°C±5°C 2. t=1000hrs(-24hrs,+72hrs) | The purpose of this is the resistance of the device which is laid under condition of high temperature for hours. |
| Low Temperature Storage Test | JIS C 7021:B-12 | 1. Ta=-40°C±5°C 2. t=1000hrs(-24hrs,+72hrs) | The purpose of this is the resistance of the device which is laid under condition of low temperature for hours. |
| High Temperature High Humidity Test | JIS C 7021:B-11 MIL-STD-202:103B | 1. Ta=65°C±5°C 2. RH=90%~95% 3. Tt=240hrs±2hrs | The purpose of this id the resistance of the device which is laid under condition of low temperature for hours. |
| Thermal Shock Test | MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1011 | 1. Ta=105 °C ±5 °C & -40 °C ±5 °C (10min)(10min) | The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature. |
| Solder Resistance Test | JIS C 7021:A-1 MIL-STD-202:210A MIL-STD-750:2031 | 1.T.Sol=260°C±5°C 2.Dwell time=10±1sec. | This test intended to determine the thermal characteristic resistance of the device to sudden exposures at ex treme changes in temperature when soldering the lead wire. |
| Solderability Test | JIS C 7021:A-2 MIL-STD-202:208D MIL-STD-750:2026 MIL-STD-883:2003 | 1.T.Sol=230°C±5°C 2.Dwell time=5±1sec. | This test intended to see soldering well performed or not. |

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